

Title (en)  
Wafer processing method

Title (de)  
Waferverarbeitungsverfahren

Title (fr)  
Procédé de traitement de plaque

Publication  
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Application  
**EP 14168599 A 20140516**

Priority  
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Abstract (en)  
The invention relates to a wafer processing method performed subsequent to cutting (1), the wafer processing method comprising: a) a step of transporting (2); b) a first wafer processing step comprising charging (4) the wafer receiving container (17) with a first processing fluid (21); c) a step of removing (5) the first processing fluid (21) from the wafer receiving container (17); d) a second wafer processing step by charging (7) the wafer receiving container (17) with a second processing fluid (22), wherein preferably the second processing fluid (22) is different from the first processing fluid (21); wherein the wafer block (16) is accommodated in the wafer receiving container (17) during the steps a) to d) without removing it from the wafer receiving container (17) between those steps.

IPC 8 full level  
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Citation (applicant)  
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